

DATA SHEET

BYC10-600CT

Dual rectifier diode
ultrafast, low switching loss

Product specification

March 2001



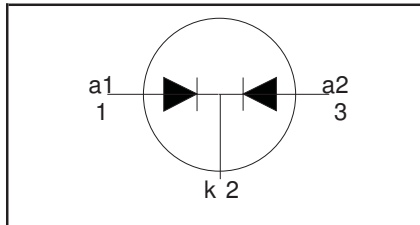
Rectifier diode ultrafast, low switching loss

BYC10-600CT

FEATURES

- Dual diode
- Extremely fast switching
- Low reverse recovery current
- Low thermal resistance
- Reduces switching losses in associated MOSFET

SYMBOL



QUICK REFERENCE DATA

$V_R = 600\text{ V}$
$V_F \leq 1.75\text{ V}$
$I_{O(AV)} = 10\text{ A}$
$t_{rr} = 19\text{ ns (typ)}$

APPLICATIONS

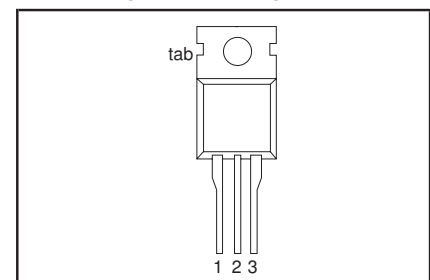
- Active power factor correction
- Half-bridge lighting ballasts
- Half-bridge/ full-bridge switched mode power supplies.

The BYC10-600CT is supplied in the SOT78 (TO220AB) conventional leaded package.

PINNING

PIN	DESCRIPTION
1	anode 1
2	cathode
3	anode 2
tab	cathode

SOT78 (TO220AB)



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{RRM}	Peak repetitive reverse voltage		-	600	V
V_{RWM}	Crest working reverse voltage		-	600	V
V_R	Continuous reverse voltage	$T_{mb} \leq 110\text{ °C}$	-	500	V
$I_{O(AV)}$	Average output current (both diodes conducting)	$\delta = 0.5$; with reapplied $V_{RRM(max)}$; $T_{mb} \leq 50\text{ °C}^1$	-	10	A
I_{FRM}	Repetitive peak forward current per diode	$\delta = 0.5$; with reapplied $V_{RRM(max)}$; $T_{mb} \leq 50\text{ °C}^1$	-	10	A
I_{FSM}	Non-repetitive peak forward current per diode	$t = 10\text{ ms}$	-	40	A
		$t = 8.3\text{ ms}$	-	44	A
		sinusoidal; $T_j = 150\text{ °C}$ prior to surge with reapplied $V_{RWM(max)}$			
T_{stg}	Storage temperature		-40	150	°C
T_j	Operating junction temperature		-	150	°C

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j-mb}$	Thermal resistance junction to mounting base	per diode	-	-	2.5	K/W
		both diodes	-	-	2.2	K/W
$R_{th\ j-a}$	Thermal resistance junction to ambient	in free air.	-	60	-	K/W

¹ $T_{mb(max)}$ limited by thermal runaway

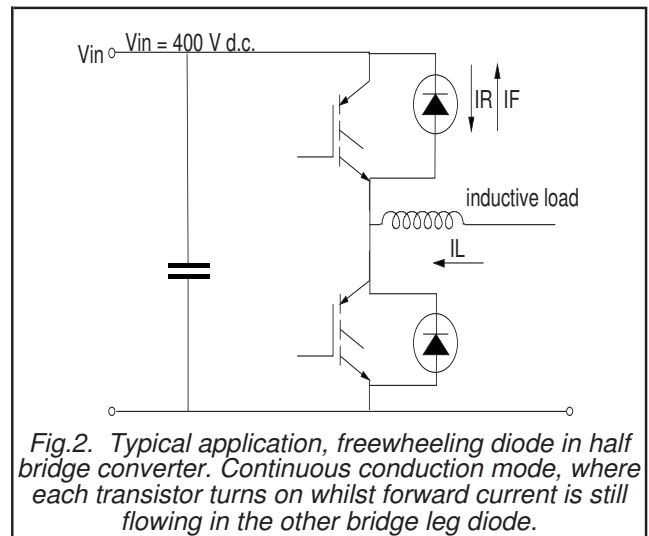
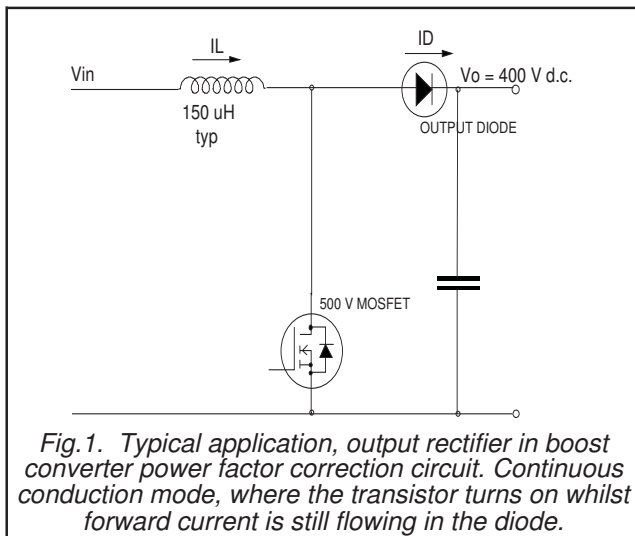
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ELECTRICAL CHARACTERISTICS

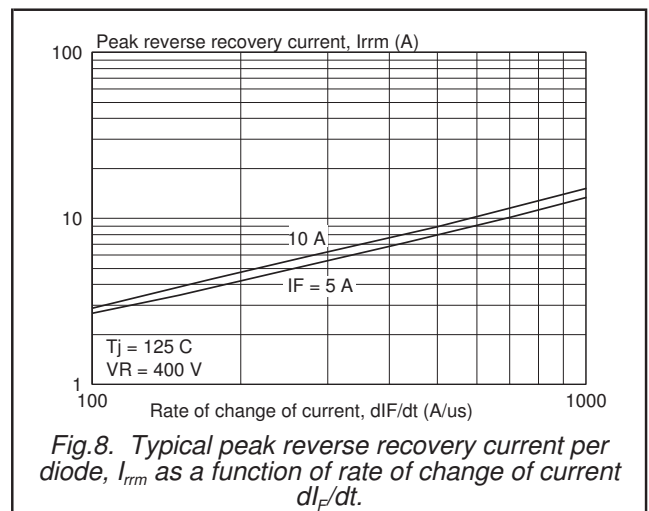
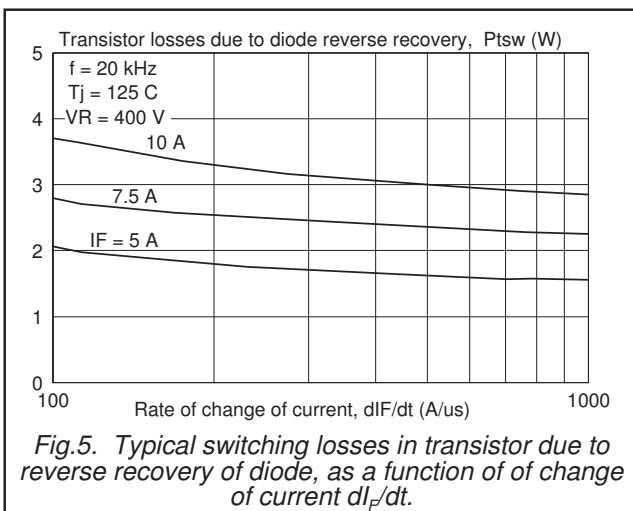
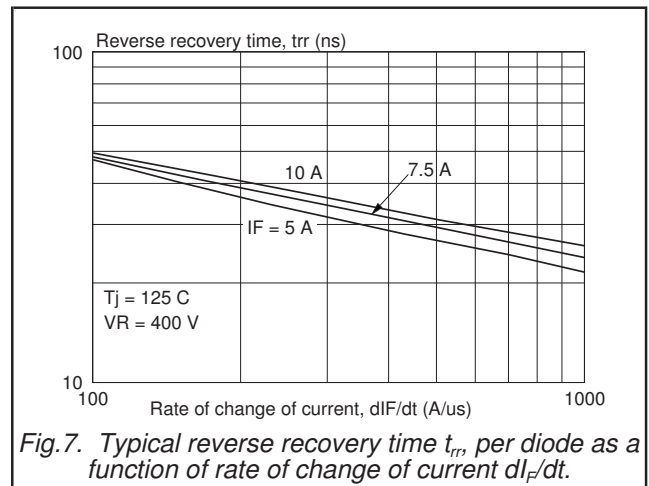
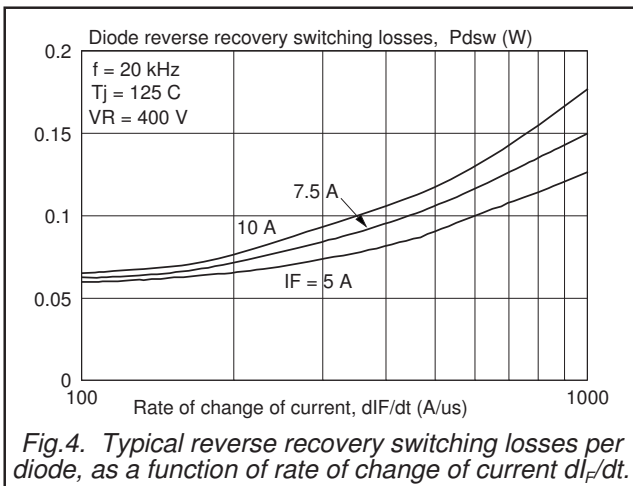
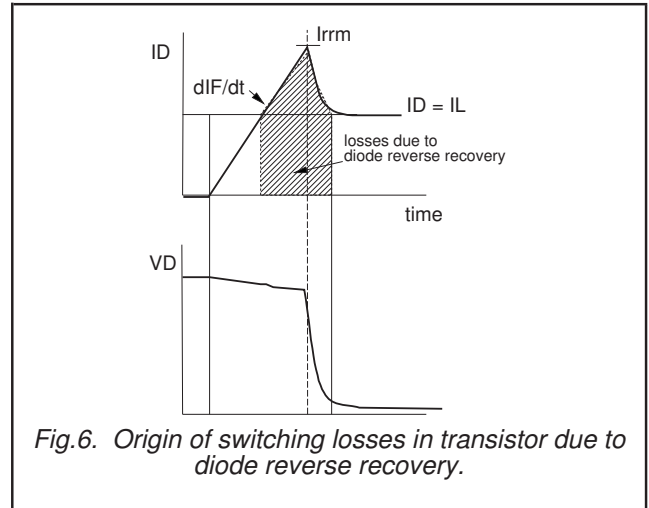
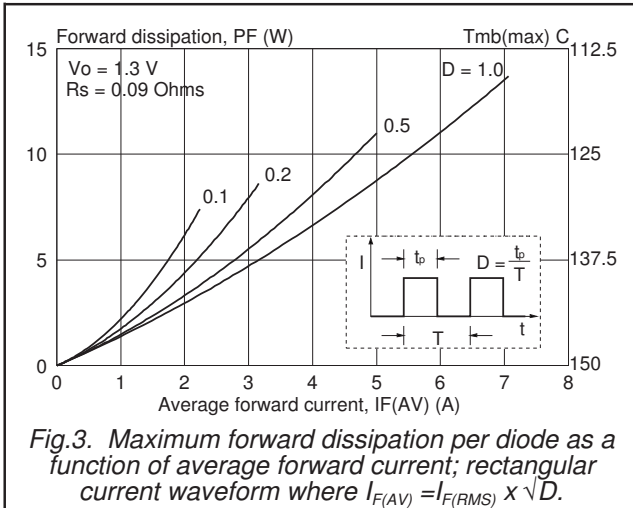
$T_j = 25\text{ }^\circ\text{C}$, per diode unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_F	Forward voltage	$I_F = 5\text{ A}; T_j = 150\text{ }^\circ\text{C}$	-	1.4	1.75	V
		$I_F = 10\text{ A}; T_j = 150\text{ }^\circ\text{C}$	-	1.75	2.2	V
I_R	Reverse current	$I_F = 5\text{ A}; V_R = 600\text{ V}$	-	2.0	2.9	V
		$V_R = 500\text{ V}; T_j = 100\text{ }^\circ\text{C}$	-	9	100	μA
			-	0.9	3.0	mA
t_{rr}	Reverse recovery time	$I_F = 1\text{ A}; V_R = 30\text{ V}; dI_F/dt = 50\text{ A}/\mu\text{s}$	-	30	50	ns
t_{rr}	Reverse recovery time	$I_F = 5\text{ A}; V_R = 400\text{ V}; dI_F/dt = 500\text{ A}/\mu\text{s}$	-	19	-	ns
t_{rr}	Reverse recovery time	$I_F = 5\text{ A}; V_R = 400\text{ V}; dI_F/dt = 500\text{ A}/\mu\text{s}; T_j = 100\text{ }^\circ\text{C}$	-	25	30	ns
I_{rrm}	Peak reverse recovery current	$I_F = 5\text{ A}; V_R = 400\text{ V}; dI_F/dt = 50\text{ A}/\mu\text{s}; T_j = 125\text{ }^\circ\text{C}$	-	0.7	3	A
I_{rrm}	Peak reverse recovery current	$I_F = 5\text{ A}; V_R = 400\text{ V}; dI_F/dt = 500\text{ A}/\mu\text{s}; T_j = 125\text{ }^\circ\text{C}$	-	8	11	A
V_{fr}	Forward recovery voltage	$I_F = 10\text{ A}; dI_F/dt = 100\text{ A}/\mu\text{s}$	-	9	11	V



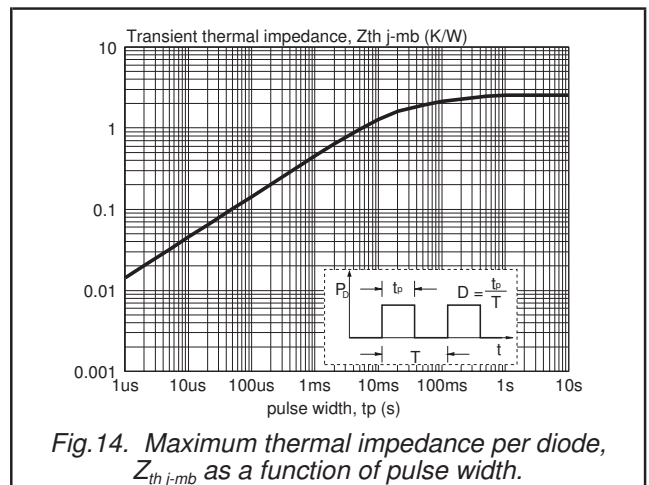
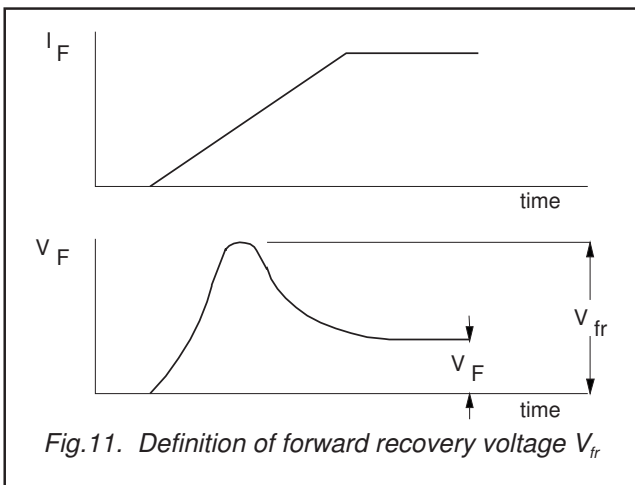
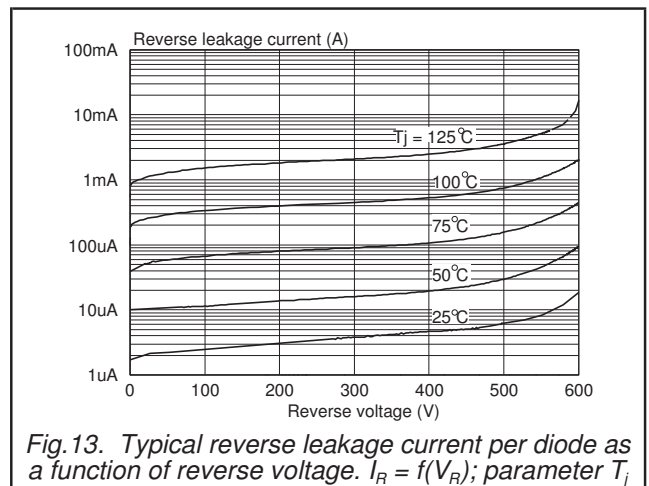
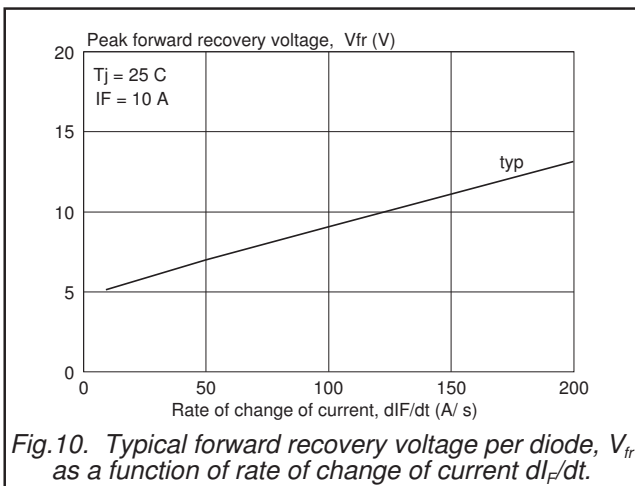
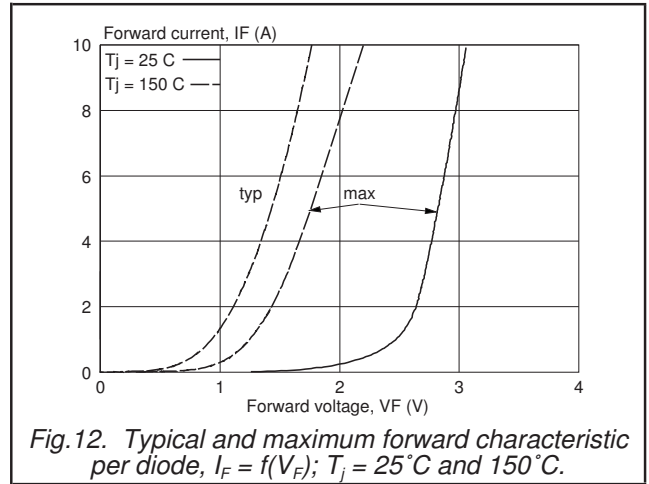
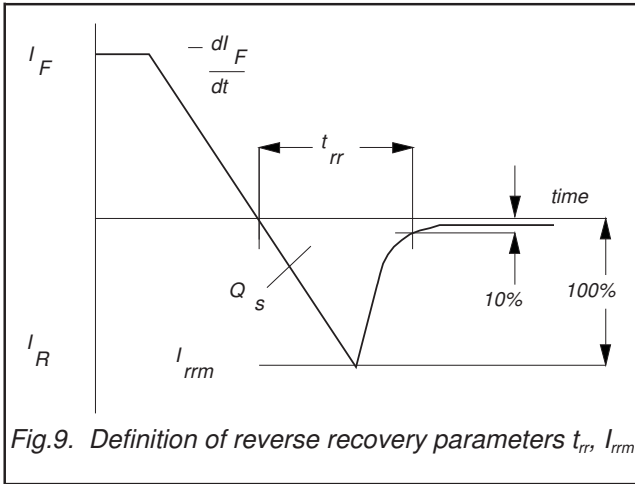
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MECHANICAL DATA

Dimensions in mm

Net Mass: 2 g

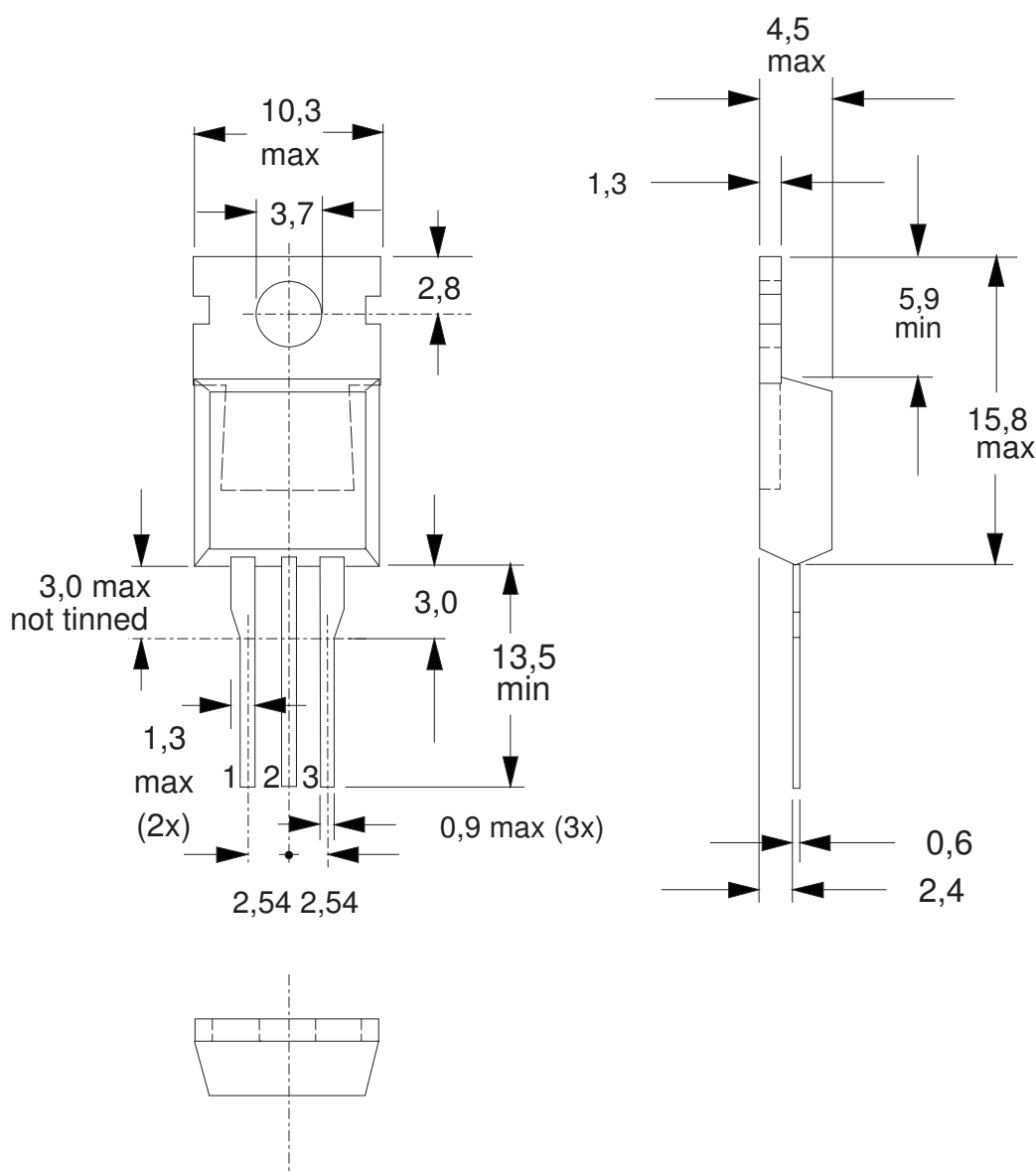


Fig.15. SOT78 (TO220AB); pin 2 connected to mounting base.

Notes

1. Refer to mounting instructions for SOT78 (TO220) envelopes.
2. Epoxy meets UL94 V0 at 1/8".

Legal information

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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